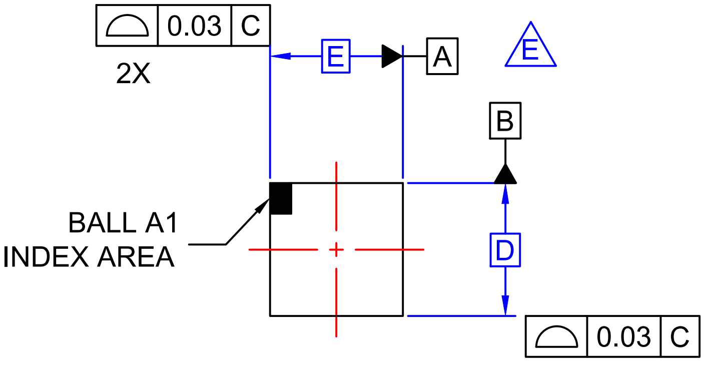
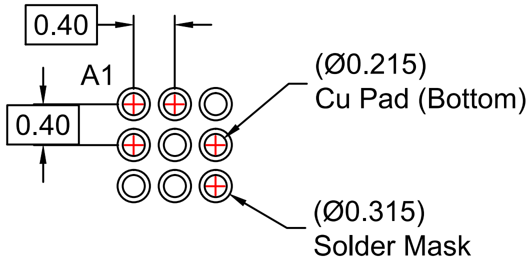
WLCSP9 1.385x1.215x0.581

CASE 567SV
ISSUE O

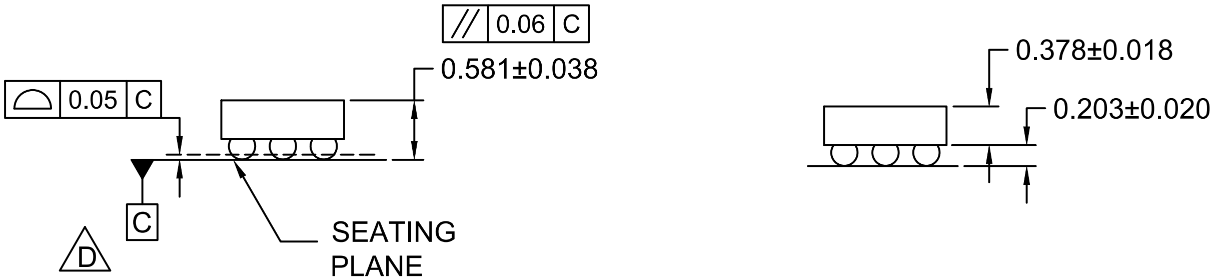
DATE 30 NOV 2016



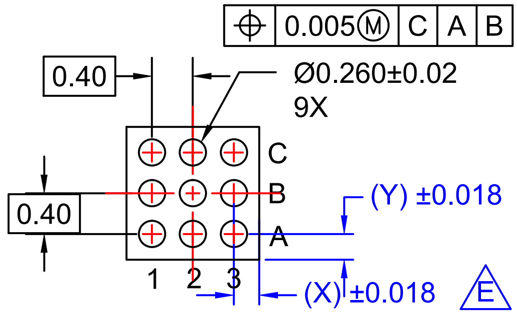
TOP VIEW



RECOMMENDED LAND PATTERN
(NSMD PAD TYPE)



SIDE VIEWS



BOTTOM VIEW

NOTES

A. NO JEDEC REGISTRATION APPLIES.
B. DIMENSIONS ARE IN MILLIMETERS.
C. DIMENSIONS AND TOLERANCE PER ASME Y14.5M, 2009.
D. DATUM C IS DEFINED BY THE SPHERICAL CROWNS OF THE BALLS.
E. FOR DIMENSIONS D,E,X, AND Y SEE PRODUCT DATASHEET.

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DESCRIPTION:	**WLCSP9 1.385x1.215x0.581**	**PAGE 1 OF 1**

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